

In the Claims

Claims 1-49 are canceled.

50. [Previously Presented] A wireless communication device comprising:
a housing including an upper surface, a lower surface, and at least one side intermediate the upper surface and the lower surface and having a dimension less than smallest dimensions of the upper surface and the lower surface, and the at least one side surface having visibly perceptible indicia thereon;
communication circuitry within the housing and the communication circuitry being configured to communicate wireless signals comprising microwave signals individually having a frequency in excess of about 900 MHZ; and
wherein the communication circuitry comprises radio frequency identification device circuitry.

51. [Previously Presented] The device according to claim 50 wherein the housing comprises an encapsulant which contacts the communication circuitry.

52. [Previously Presented] The device according to claim 50 wherein the at least one side surface has a dimension less than about 100 mils.

53. Canceled.

54. [Previously Presented] A wireless communication device comprising:
a substrate having a support surface defined by a perimetral edge;
communication circuitry elevationally over the support surface of the substrate and
configured to communicate wireless signals comprising microwave signals; and
an encapsulant elevationally over the support surface and configured to encapsulate
at least portions of the support surface of the substrate and the communication circuitry,
and wherein the encapsulant and the substrate respectively define an upper surface and
a lower surface and have a thickness less than a smallest dimension of the perimetral
edge, and the encapsulant includes visibly perceptible indicia intermediate the upper
surface and the lower surface.

55. [Previously Presented] The device according to claim 54 wherein the support
surface comprises a surface substantially in the shape of a rectangle.

56. [Previously Presented] The device according to claim 54 wherein the
encapsulant contacts at least portions of the support surface and the communication
circuitry.

57. [Previously Presented] The device according to claim 54 wherein the
encapsulant and the substrate have a thickness less than about 100 mils.

58. [Previously Presented] The device according to claim 54 wherein the
communication circuitry comprises radio frequency identification device circuitry.

59. [Previously Presented] A wireless communication device comprising:
communication circuitry configured to communicate wireless signals; and
an encapsulant configured to encapsulate and contact at least a portion of the
communication circuitry, wherein the encapsulant defines at least one side surface and the
at least one side surface has visibly perceptible information thereon.

60. [Previously Presented] The device according to claim 59 wherein the at least
one side surface of the encapsulant has a thickness less than about 100 mils.

61. [Previously Presented] The device according to claim 59 wherein the
communication circuitry comprises radio frequency identification device circuitry.

62. [Previously Presented] A radio frequency identification device comprising:
a housing including an upper surface and a lower surface which define a housing
thickness of less than about 100 mils intermediate the lower surface and the upper surface,
and the housing has visibly perceptible indicia thereon intermediate the upper surface and
the lower surface; and

communication circuitry within the housing and configured to communicate wireless
signals comprising microwave signals.

63. [Previously Presented] The device according to claim 62 wherein the housing
comprises an encapsulant which contacts at least portions of the support surface and the
communication circuitry.

64. [Previously Presented] The device according to claim 62 further comprising an antenna within the housing and coupled with the communication circuitry.

65. [Previously Presented] A radio frequency identification device comprising:
a substrate having a support surface;
radio frequency identification device circuitry elevationally over the support surface and configured to communicate wireless signals comprising microwave signals;
a power source elevationally over the support surface and coupled with the radio frequency identification device circuitry, wherein the power source comprises a battery;
an antenna elevationally over the support surface and coupled with the radio frequency identification device circuitry; and
an encapsulant contacting at least portions of the support surface, the radio frequency identification device circuitry, the power source and the antenna, wherein the encapsulant and the substrate form a housing having an upper surface and a lower surface interconnected by at least one side surface, and the at least one side surface has a dimension less than smallest dimensions of the upper and lower surfaces, and the at least one side surface includes visibly perceptible indica.

66. [Previously Presented] A method of forming a wireless communication device comprising:

providing communication circuitry configured to communicate wireless signals;
providing a housing including an upper surface, a lower surface and at least one side surface about the communication circuitry, the at least one side surface has a

dimension less than smallest dimensions of the upper surface and the lower surface;

providing visibly perceptible indicia on the at least one side surface; and

wherein the providing communication circuitry comprises providing radio frequency identification device circuitry configured to communicate microwave wireless signals.

67. [Previously Presented] The method according to claim 66 wherein the providing the housing comprises encapsulating at least a portion of the communication circuitry with an encapsulant.

68. [Previously Presented] The method according to claim 67 wherein the encapsulating comprises contacting at least the encapsulated portion of the communication circuitry with the encapsulant.

69. [Previously Presented] The method according to claim 66 wherein the at least one side surface has a dimension less than about 100 mils.

70. Canceled.

71. [Previously Presented] A method of forming a wireless communication device comprising:

providing a substrate having a support surface defined by at least one perimetral edge;

providing communication circuitry elevationally over the support surface of the

substrate and configured to communicate wireless signals;

encapsulating at least portions of the support surface of the substrate and the communication circuitry using an encapsulant, the encapsulant and the substrate respectively define an upper surface and a lower surface and have a thickness less than a smallest dimension of the at least one perimetral edge; and

providing visibly perceptible indicia on the encapsulant intermediate the upper surface and the lower surface.

72. [Previously Presented] The method according to claim 71 wherein the providing the substrate comprises providing the substrate having a substantially rectangular shape.

73. [Previously Presented] The method according to claim 71 wherein the encapsulating comprises contacting at least the encapsulated portions of the support surface of the substrate and the communication circuitry with the encapsulant.

74. [Previously Presented] The method according to claim 71 wherein the encapsulant and the substrate have a thickness less than about 100 mils.

75. [Previously Presented] The method according to claim 71 wherein the providing communication circuitry comprises providing radio frequency identification device circuitry.

76. [Previously Presented] A method of forming a wireless communication device comprising:

providing communication circuitry configured to communicate wireless signals;

encapsulating at least a portion of the communication circuitry with an encapsulant which contacts at least the encapsulated portion of the communication circuitry, the encapsulant forming at least one side surface; and

providing visibly perceptible indicia upon the at least one side surface of the encapsulant.

77. [Previously Presented] The method according to claim 76 wherein the at least one side surface of the encapsulant has a dimension less than about 100 mils.

78. [Previously Presented] The method according to claim 76 wherein the providing communication circuitry comprises providing radio frequency identification device circuitry.

79. [Previously Presented] A method of forming a radio frequency identification device comprising:

providing radio frequency identification device circuitry configured to communicate wireless signals comprising microwave signals;

providing a housing including an upper surface, a lower surface, and at least one side surface about the communication circuitry, the at least one side surface having a dimension less than about 100 mils; and

providing visibly perceptible indicia on the at least one side surface.

80. [Previously Presented] The method according to claim 79 wherein the providing the housing comprises providing an encapsulant over at least a portion of a support surface of a substrate.

81. [Previously Presented] The method according to claim 80 wherein the encapsulant contacts at least portions of the support surface and the radio frequency identification device circuitry.

82. [Previously Presented] A method of forming a radio frequency identification device comprising:

providing radio frequency identification device circuitry configured to communicate wireless signals comprising microwave signals;

coupling a power source with the radio frequency identification device circuitry;

coupling an antenna with the radio frequency identification device circuitry;

providing a housing including an upper surface, a lower surface and at least one side surface about at least portions of the radio frequency identification device circuitry, the power source and the antenna, the at least one side surface having a dimension less than smallest dimensions of the upper surface and the lower surface; and

providing visibly perceptible indicia on the at least one side surface.

83. [Previously Presented] The device according to claim 50 wherein the communication circuitry is configured to implement backscatter communications.

84. [Previously Presented] The device according to claim 50 further comprising a battery coupled with the communication circuitry.

85. [Previously Presented] The device according to claim 54 wherein the communication circuitry is configured to implement backscatter communications.

86. [Previously Presented] The device according to claim 54 further comprising a battery coupled with the communication circuitry.

87. [Previously Presented] The device according to claim 59 wherein the communication circuitry is configured to implement backscatter communications.

88. [Previously Presented] The device according to claim 59 further comprising a battery coupled with the communication circuitry.

89. [Previously Presented] The device according to claim 62 wherein the communication circuitry is configured to implement backscatter communications.

90. [Previously Presented] The device according to claim 62 further comprising a battery coupled with the communication circuitry.

91. [Previously Presented] The method according to claim 66 wherein the providing communication circuitry comprises providing backscatter communication circuitry.

92. [Previously Presented] The method according to claim 66 further comprising electrically coupling a battery with the communication circuitry.

93. [Previously Presented] The method according to claim 71 wherein the providing communication circuitry comprises providing backscatter communication circuitry.

94. [Previously Presented] The method according to claim 71 further comprising electrically coupling a battery with the communication circuitry.

95. [Previously Presented] The method according to claim 76 wherein the providing communication circuitry comprises providing backscatter communication circuitry.

96. [Previously Presented] The method according to claim 76 further comprising electrically coupling a battery with the communication circuitry.

97. [Previously Presented] The method according to claim 79 wherein the providing the radio frequency identification device circuitry comprises providing backscatter circuitry.

98. [Previously Presented] The method according to claim 79 further comprising electrically coupling a battery with the radio frequency identification device circuitry.

99. [Previously Presented] A wireless communication device comprising:
a housing including an upper surface, a lower surface, and at least one side intermediate the upper surface and the lower surface and having a dimension less than smallest dimensions of the upper surface and the lower surface, and the at least one side surface having visibly perceptible indicia thereon; and
communication circuitry within the housing and the communication circuitry being configured to communicate wireless signals;
wherein the communication circuitry is configured to implement backscatter communications.

100. [Previously Presented] A method of forming a wireless communication device comprising:
providing communication circuitry configured to communicate wireless signals;
providing a housing including an upper surface, a lower surface and at least one side surface about the communication circuitry, the at least one side surface has a dimension less than smallest dimensions of the upper surface and the lower surface; and
providing visibly perceptible indicia on the at least one side surface;
wherein the providing communication circuitry comprises providing backscatter communication circuitry.

101. [Previously Presented] The device according to claim 50 further comprising a transmit antenna configured to transmit microwave signals and a receive antenna configured to receive microwave signals.

102. [Previously Presented] The device according to claim 51 further comprising:
an antenna coupled with the communication circuitry and configured to communicate the wireless signals; and

a substrate comprising different material than the encapsulant, and wherein the encapsulant and the substrate encapsulate an entirety of the communication circuitry and the antenna.

103. [Previously Presented] The device according to claim 54 wherein the substrate and the encapsulant comprise different materials.

104. [Previously Presented] The device according to claim 54 wherein the substrate and the encapsulant form a solid mass substantially free of any void space.

105. [Previously Presented] The device according to claim 54 further comprising an antenna coupled with the communication circuitry and configured to communicate the wireless signals, and wherein the substrate and the encapsulant encapsulate an entirety of the communication circuitry and the antenna.

106. [Previously Presented] The method according to claim 66 wherein the providing the housing comprises:

providing a substrate;

flowing a flowable encapsulant over the substrate; and

curing the flowable encapsulant into a solid mass substantially free of any void space.

107. Cancel.